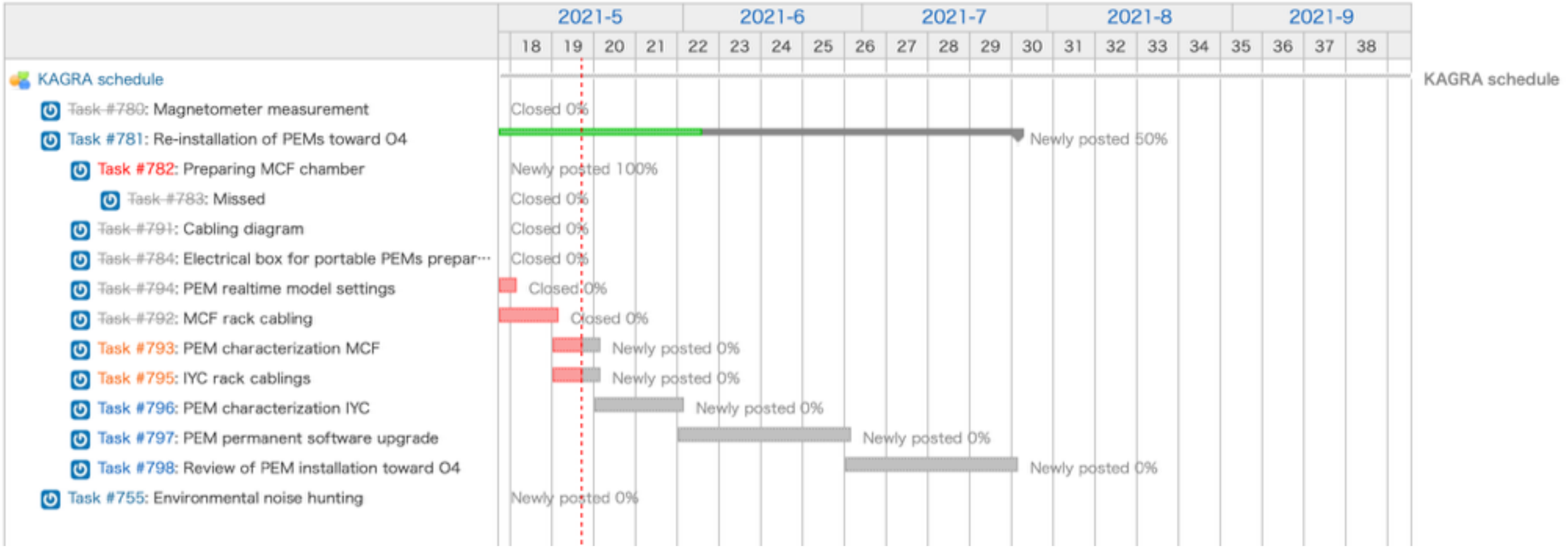
PEM meeting

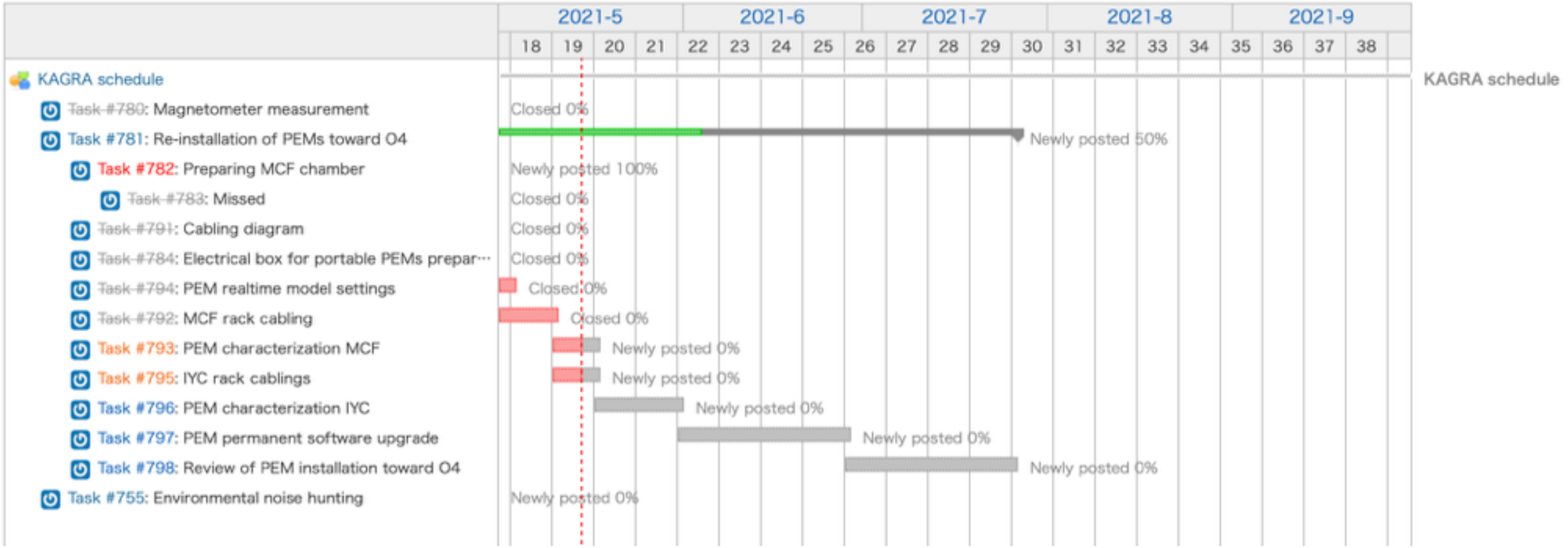
2021-05-14
Takaaki Yokozawa

1. PEM scheduling



- MCF rack preparation
  - AA0, WF0, WF1 ready
  - AA1, AI0 ongoing(?)

1. PEM scheduling



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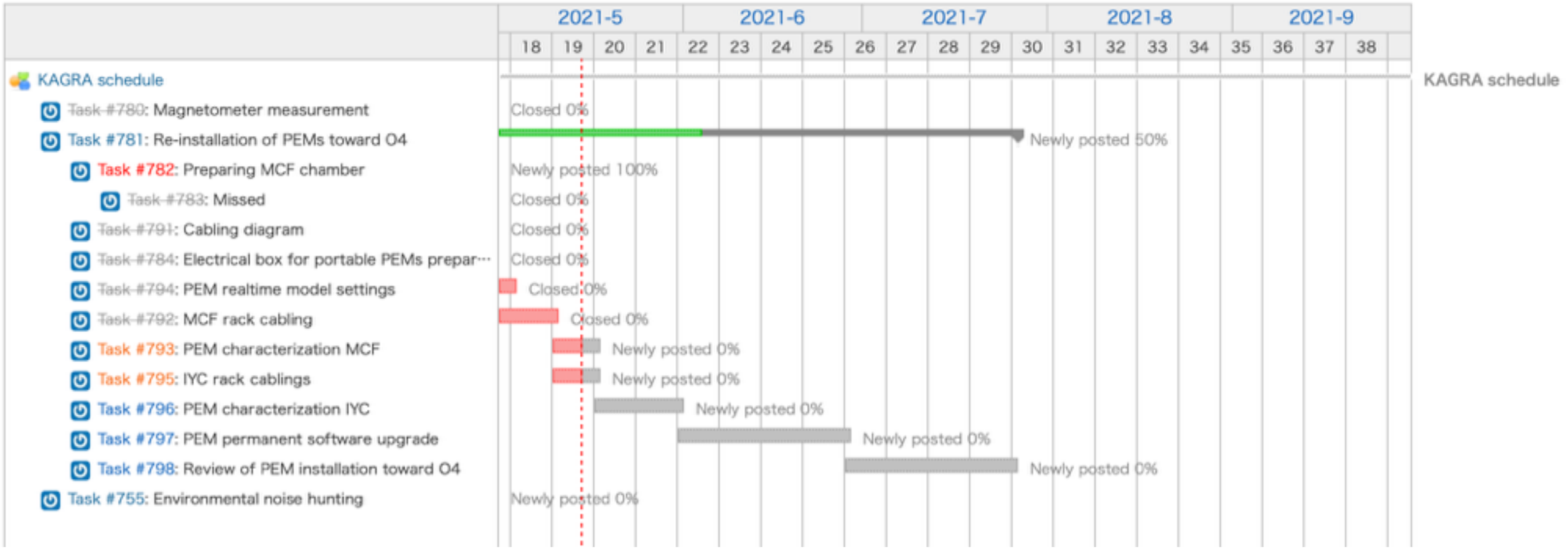
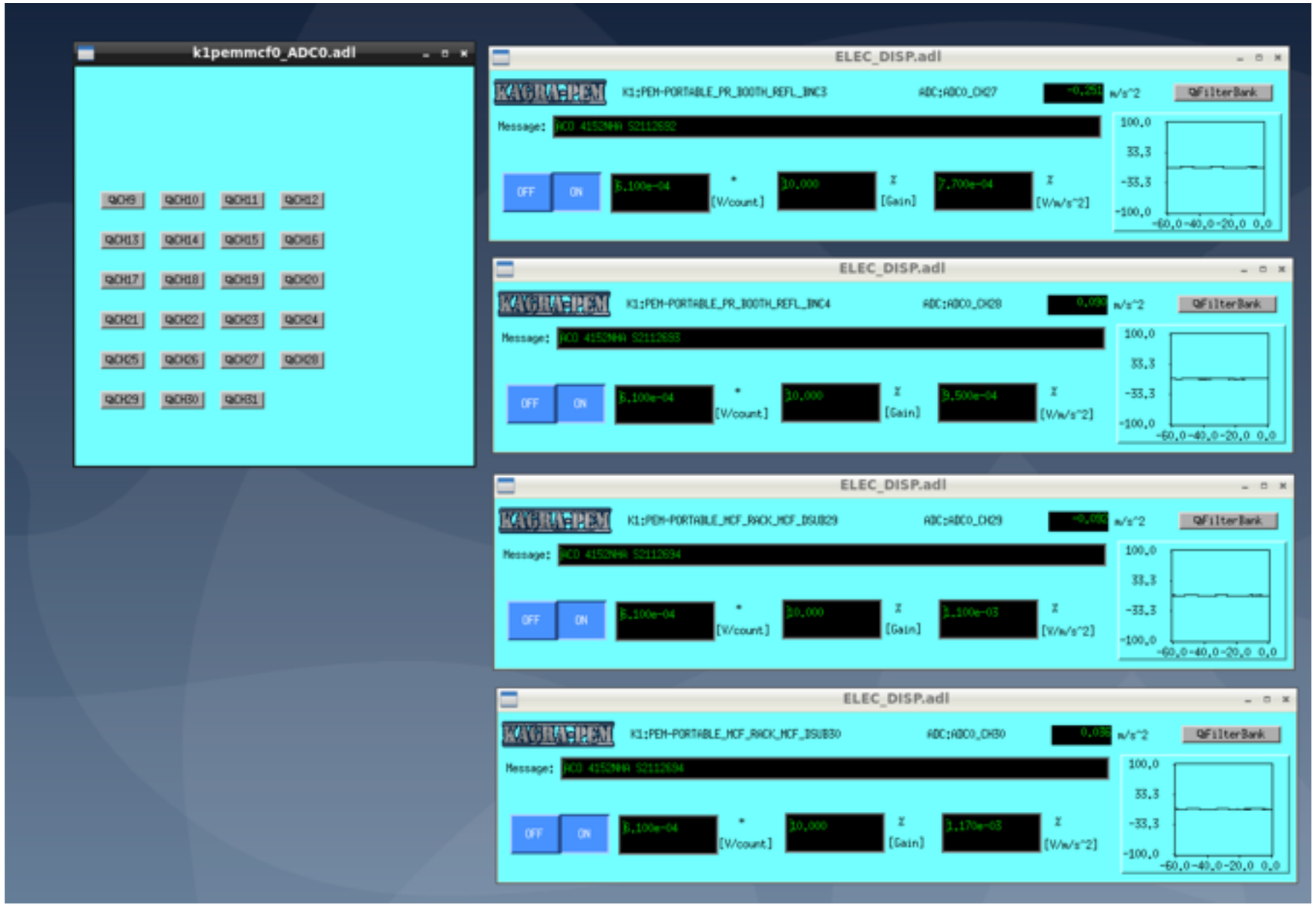


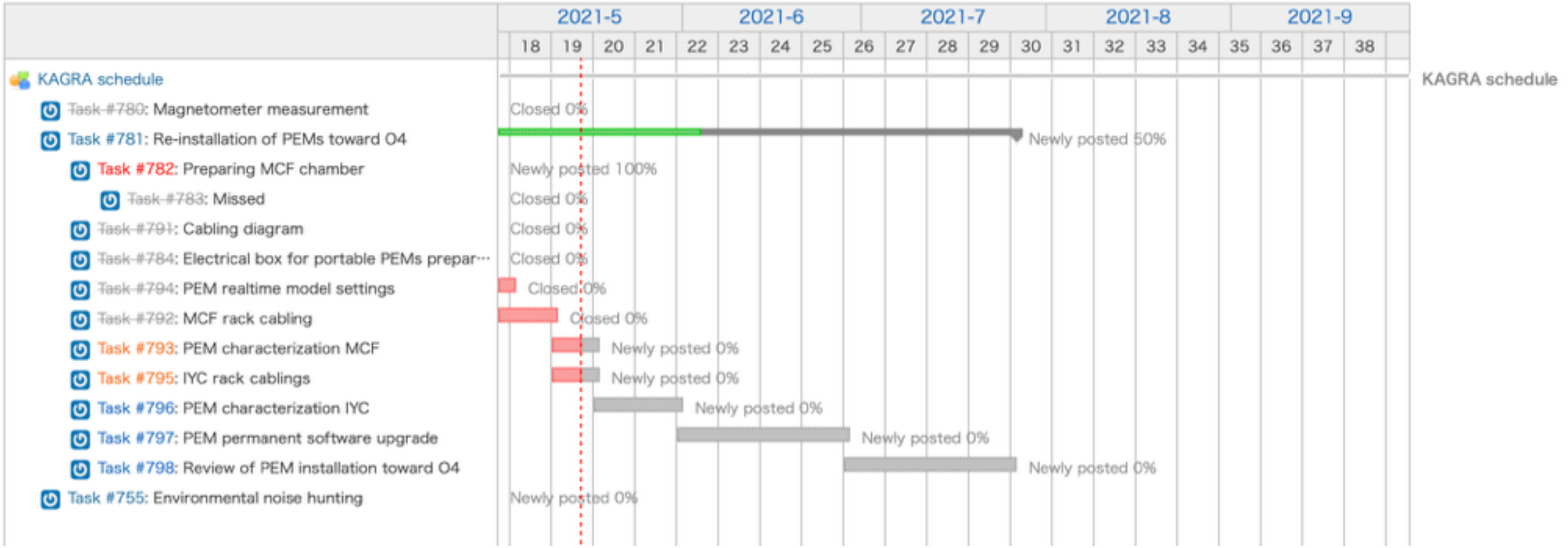
- Realtime model setting -> Ready

1. PEM scheduling



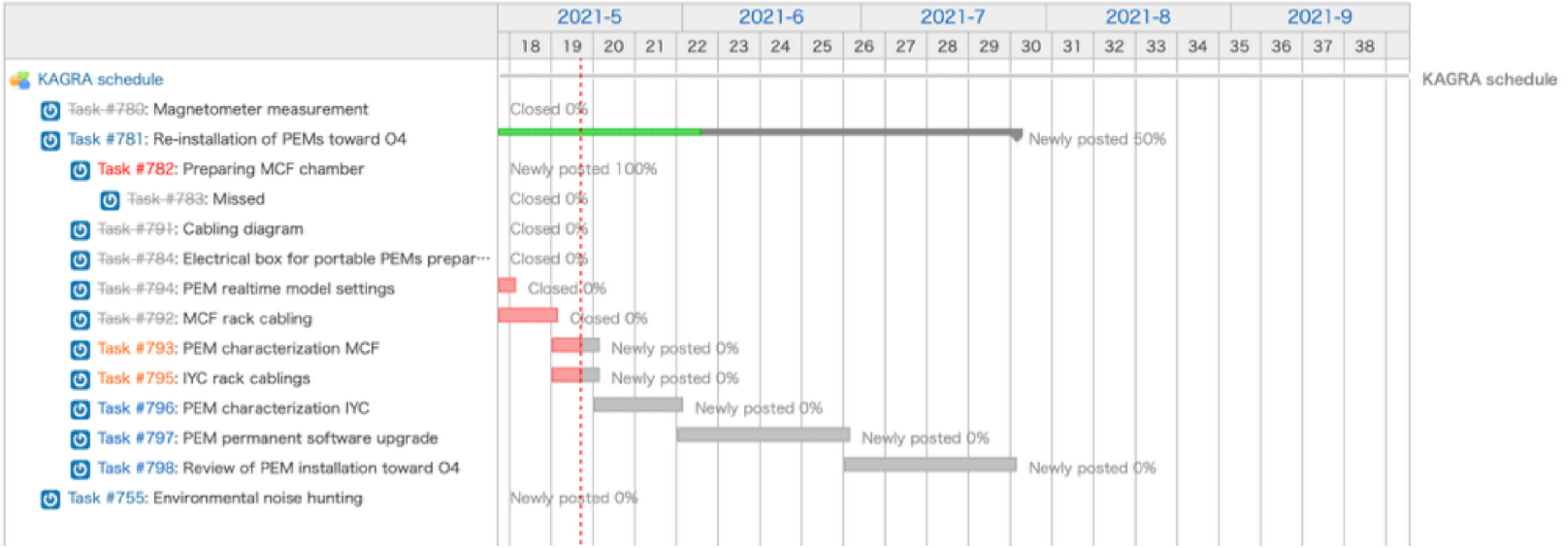
- Realtime model setting -> Ready
  - Set calibration factors from medm screen

1. PEM scheduling



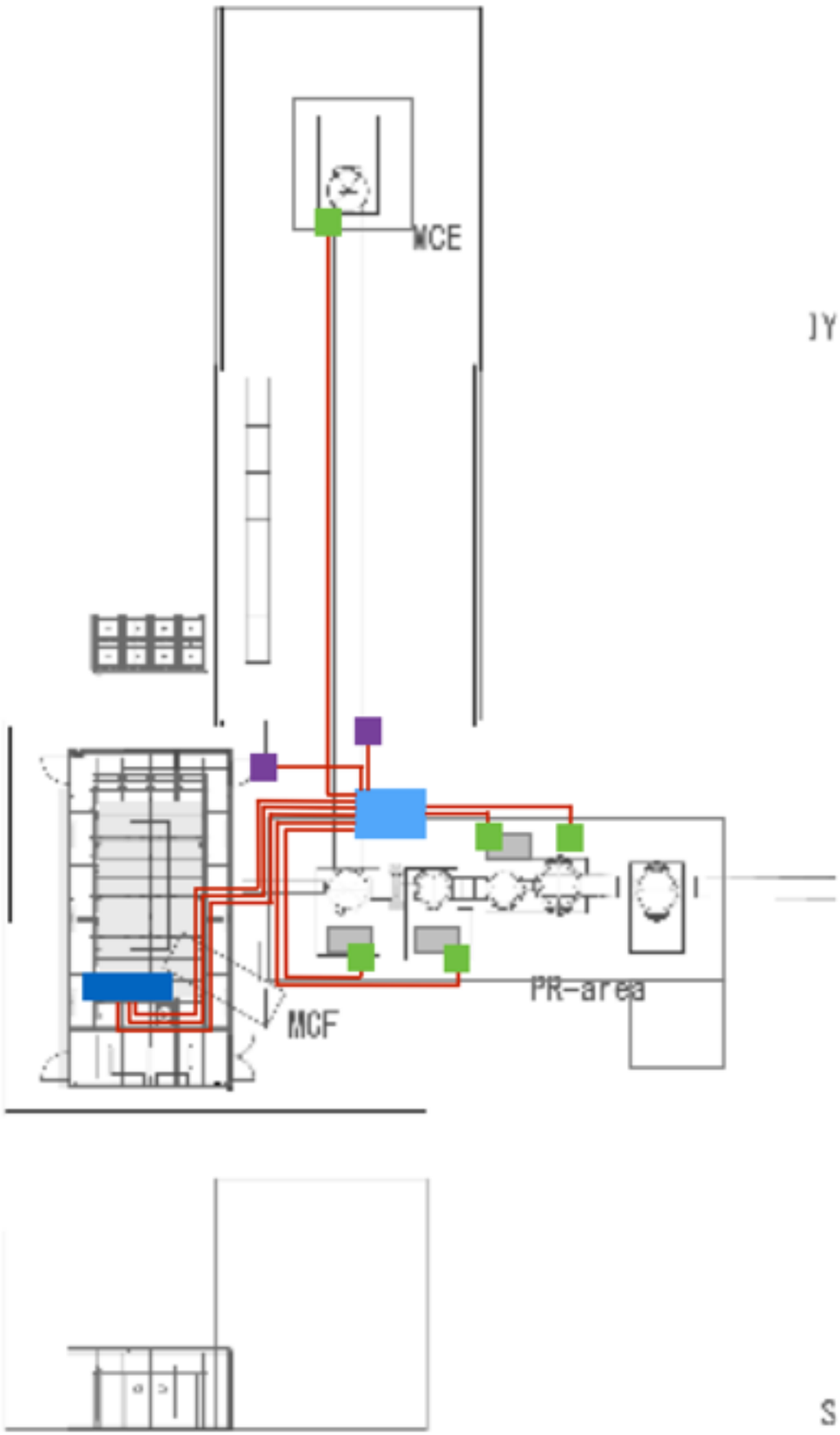
- Preparation of electrical box -> Ready
  - ACO power in the box
  - AC power supply
  - Cable fixing

1. PEM scheduling



- Cable diagram -> Done
  - Review process(JGWDoc-12884)

Cabling design



ADC0-1
SEIS_MCF_GND_X,Y,Z

Whitening

ADC0-2
SEIS_MCFTEST_GND_X,Y,Z
-> Change future

Whitening

ADC0-3
ACC_PSL_TABLE_PSL1_Y
ACC_PSL_TABLE_PSL2_X
ACC_PSL_TABLE_PSL3_Z
PORTABLE_PSL_BOOTH_PSL_BNC4

ADC0-4
ACC_PSL_PERI_PSL1_Y
ACC_PSL_PERI_PSL2_X
ACC_PSL_PORTABLE1
ACC_PSL_PORTABLE2

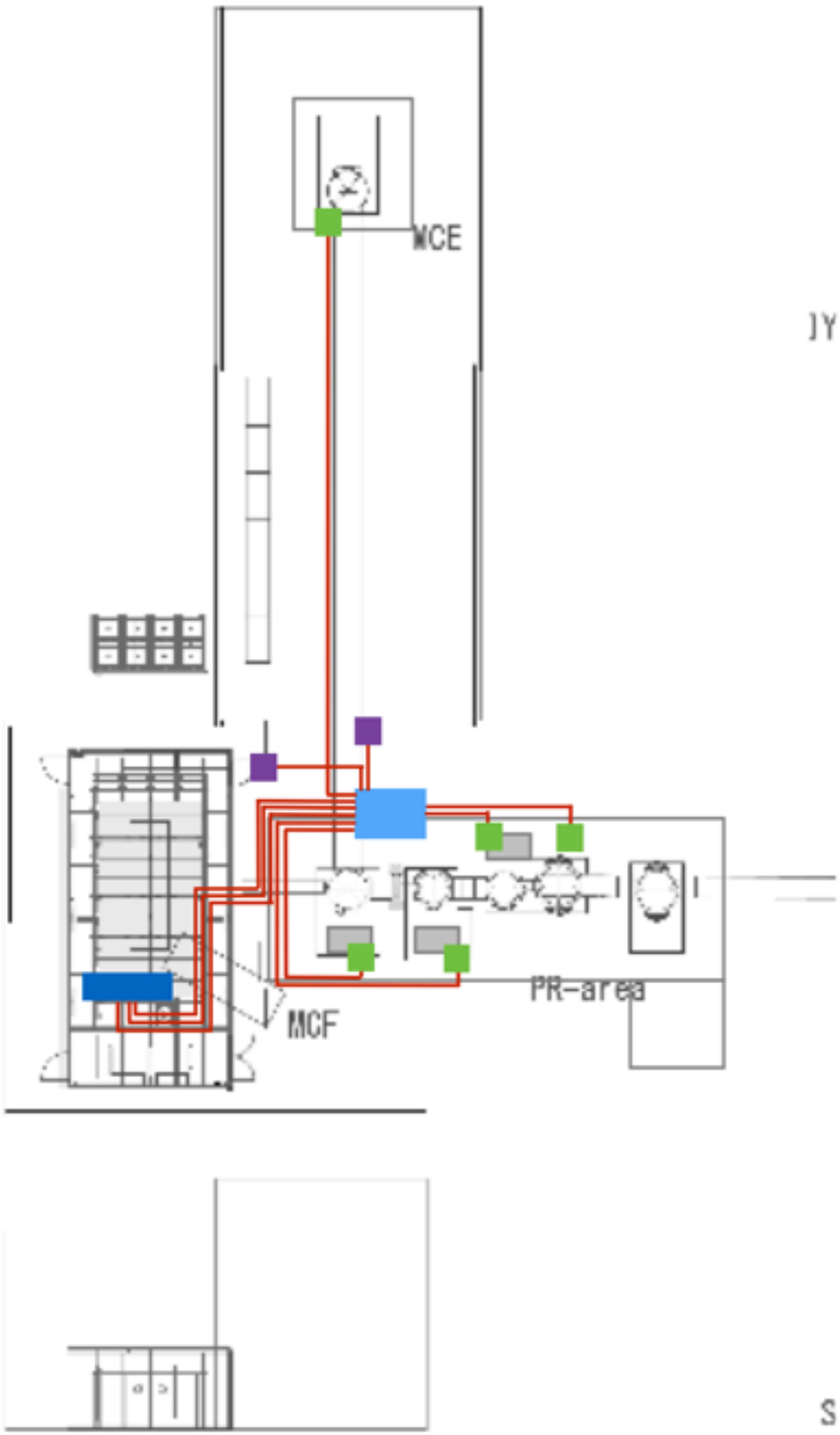
ADC0-5
MIC_PSL_TABLE_PSL1_Z
MIC_PSL_TABLE_PSL2_Z
MIC_PSL_TABLE_PSL3_Z
PORTABLE_PSL_BOOTH_PSL_BNC4

ADC0-6
ACC_MCF_TABLE_IMCREFL_Z
MIC_MCF_TABLE_IMCREFL_Z
PORTABLE_MCF_BOOTH_IMCREFL_BNC3,4

ADC0-7
ACC_PR_TABLE_REFL_Z
MIC_PR_TABLE_REFL_Z
PORTABLE_PR_BOOTH_REFL_BNC3,4

ADC0-8
PORTABLE_MCF_RACK_MCF_DSUB29,30,31

Cabling design



ADC1-1
ACC_MCE_BOOTH_IMCTRANS_Z
MIC_MCE_BOOTH_IMCTRANS_Z
PORTABLE_MCE_BOOTH_IMCTRANS_BNC3,4

ADC1-2
ACC_PR_TABLE_ISS_Z
MIC_PR_TABLE_ISS_Z
PORTABLE_PR_BOOTH_ISS_BNC3,4

ADC1-3
MIC_MCF_BOOTH_MCF_Z
PORTABLE_MCF_BOOTH_MCF_BNC2,3,4

ADC1-4
MIC_PR_BOOTH_PR_Z
PORTABLE_PR_BOOTH_PRM_BNC2,3,4

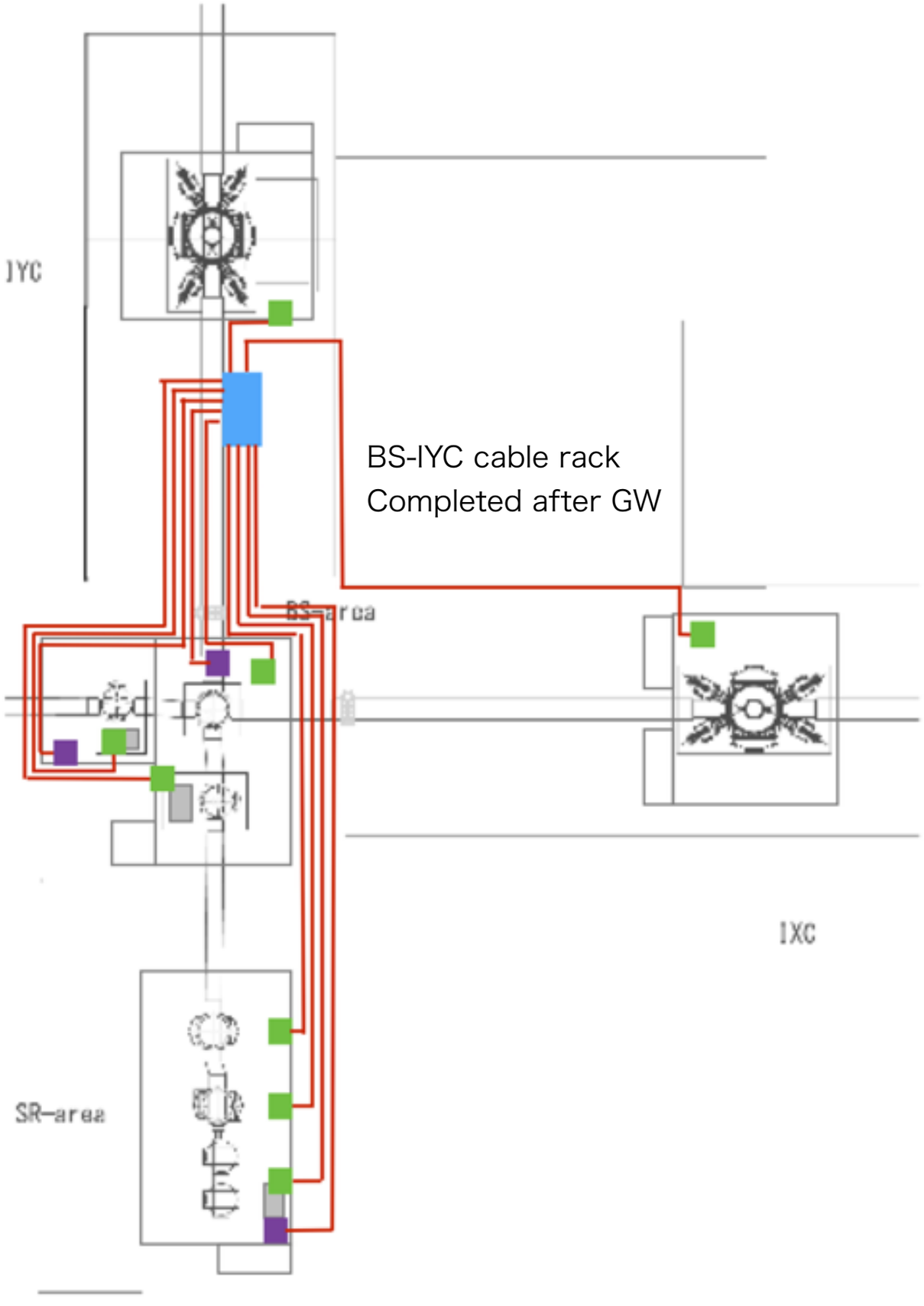
ADC1-5
Volt PSL
Volt IMCREFL
Volt REFL
Volt ISS

ADC1-6

ADC0-7

ADC0-8

Cabling design



ADC0-1
PORTABLE_IY0_RACK_IY0_DSUB_1,2,3,4

ADC0-2
PORTABLE_IY0_RACK_IY0_DSUB_5,6,7,8

ADC0-3
SEIS_OMC_GND_X,Y,Z — Whitening

ADC0-4
SEIS_BS_GND_X,Y,Z — Whitening

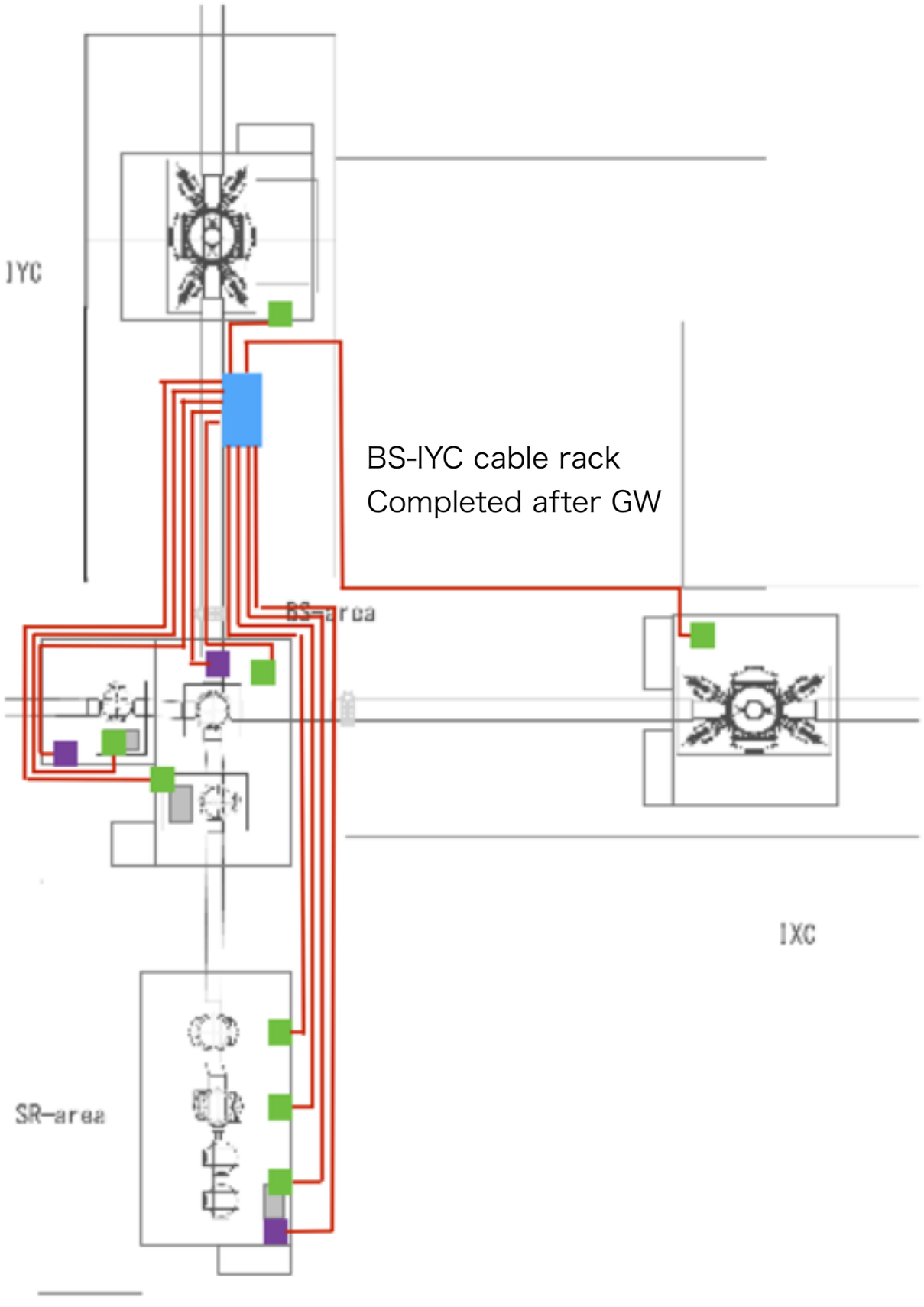
ADC0-5
MAG_BS_X,Y,Z — Whitening

ADC0-6
MIC_BS_BOOTH_BS_Z
PORTABLE_BS_BOOTH_BS_BNC2,3,4

ADC0-7
MIC_SR_BOOTH_SR_Z
PORTABLE_SR_BOOTH_SR_BNC2,3,4

ADC0-8
PORTABLE_IY_RACK_IY_DSUB_29,30,31

Cabling design



BS-IYC cable rack
Completed after GW

ADC1-1
ACC_BS_TABLE_POP_Z
MIC_BS_TABLE_POP_Z
PORTABLE_BS_BOOTH_POP_BNC3,4

ADC1-2
ACC_BS_TABLE_POS_Z
MIC_BS_TABLE_POS_Z
PORTABLE_BS_BOOTH_POS_BNC3,4

ADC1-3
ACC_OMC_TABLE_OMC_Z
MIC_OMC_TABLE_OMC_Z
ACC_OMC_BOOTH_OMM_Z
MIC_OMC_BOOTH_OMM_Z

ADC1-4
PORTABLE_OMC_BOOTH_OMC_BNC1,2,3,4

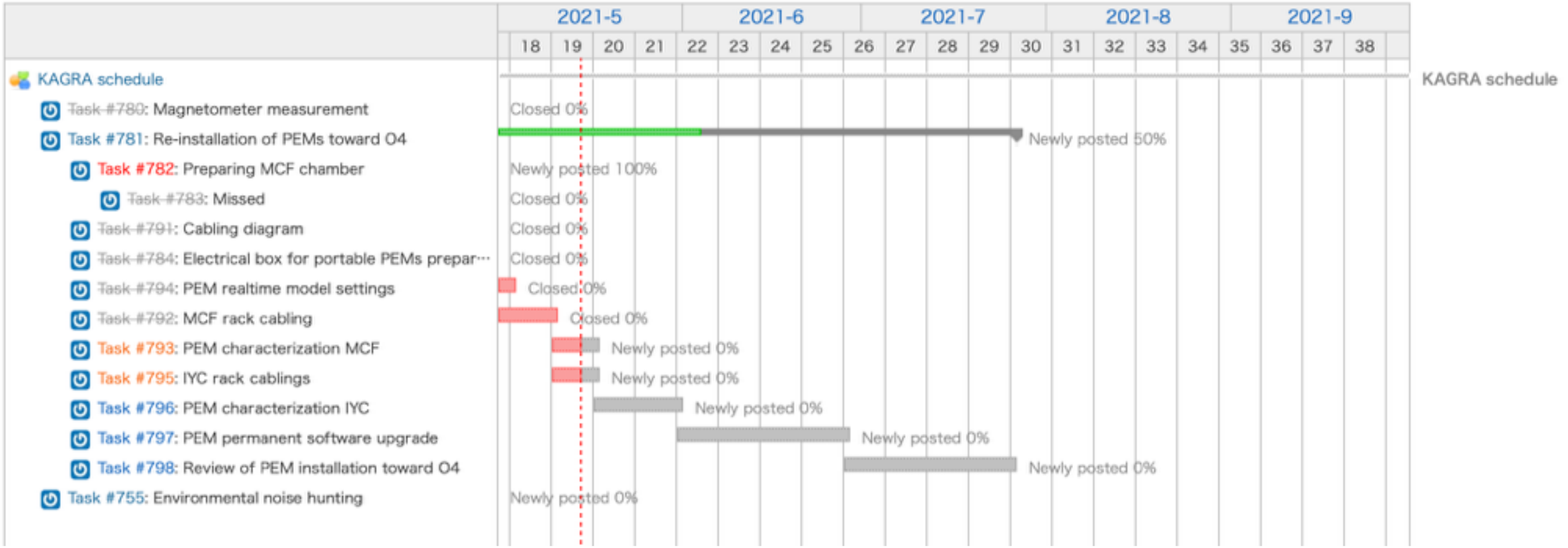
ADC1-5
ACC_IXC_BOOTH_IXC_Z
MIC_IXC_BOOTH_IXC_Z
PORTABLE_IXC_BOOTH_IXC_BNC3,4

ADC1-6
ACC_IYC_BOOTH_IYC_Z
MIC_IYC_BOOTH_IYC_Z
PORTABLE_IYC_BOOTH_IYC_BNC3,4

ADC1-7
Volt POP
Volt POS
Volt OMC
Volt OMM

ADC1-8

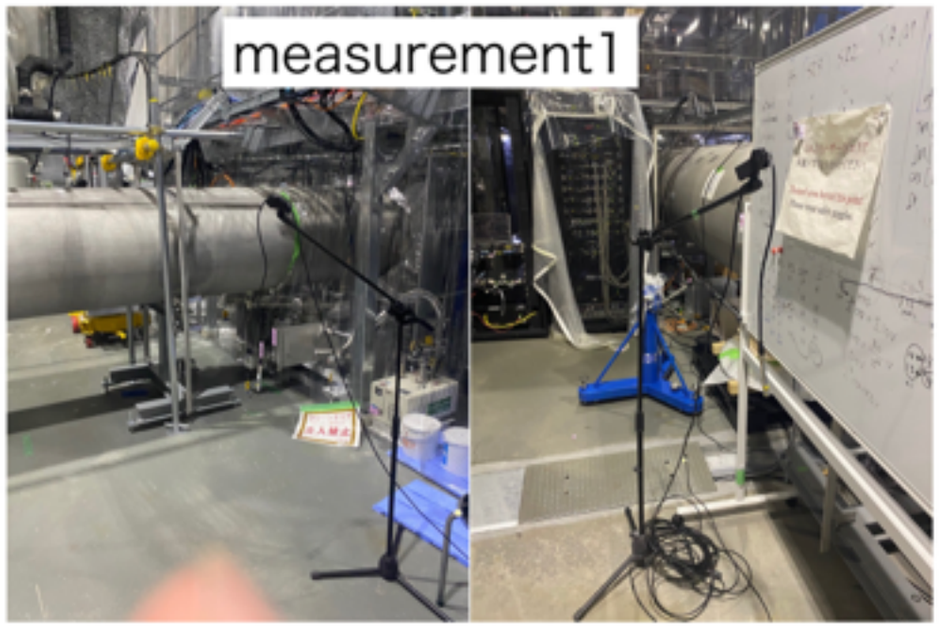
1. PEM scheduling

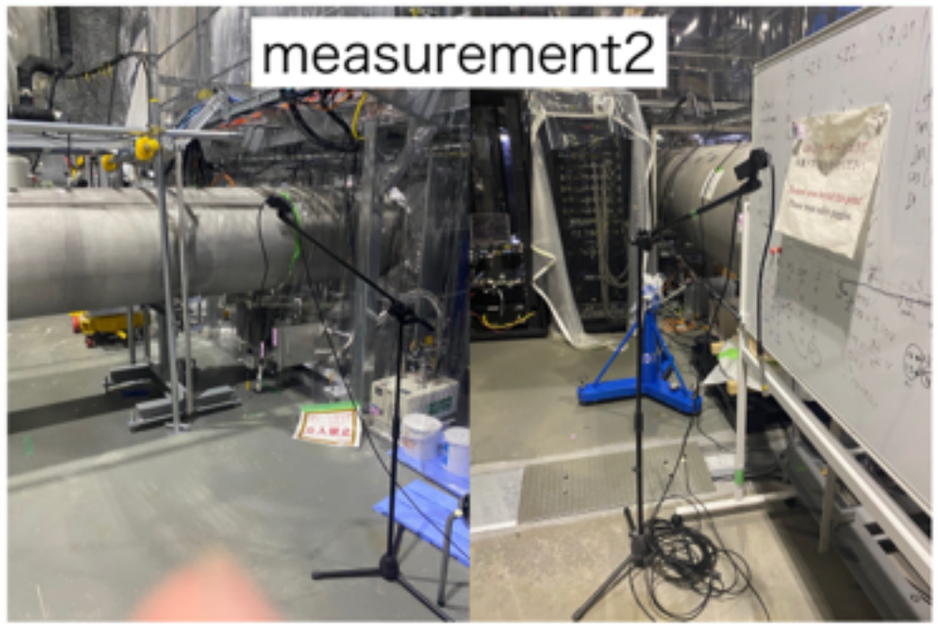


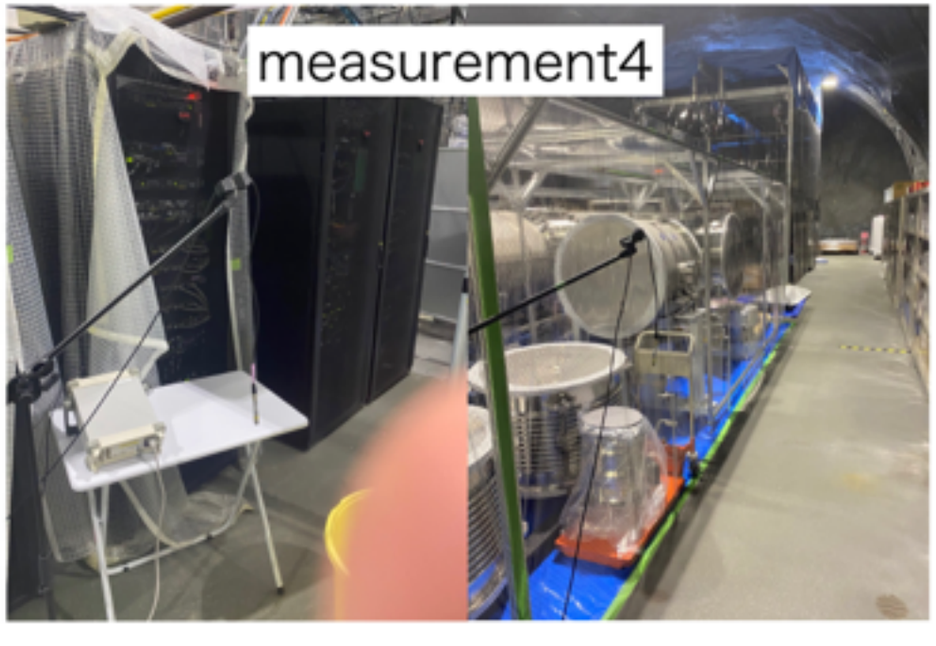
- MCF rack cabling -> Mostly done
  - set electrical rack +X side

1. Infrasound measurement

1. IMC rackの横と,BS rackの裏は常に同じ場所で測定している。
2. IMC rack付近とBS rack付近でもう一方のマイクの場所を移動させて測定をしてみた。







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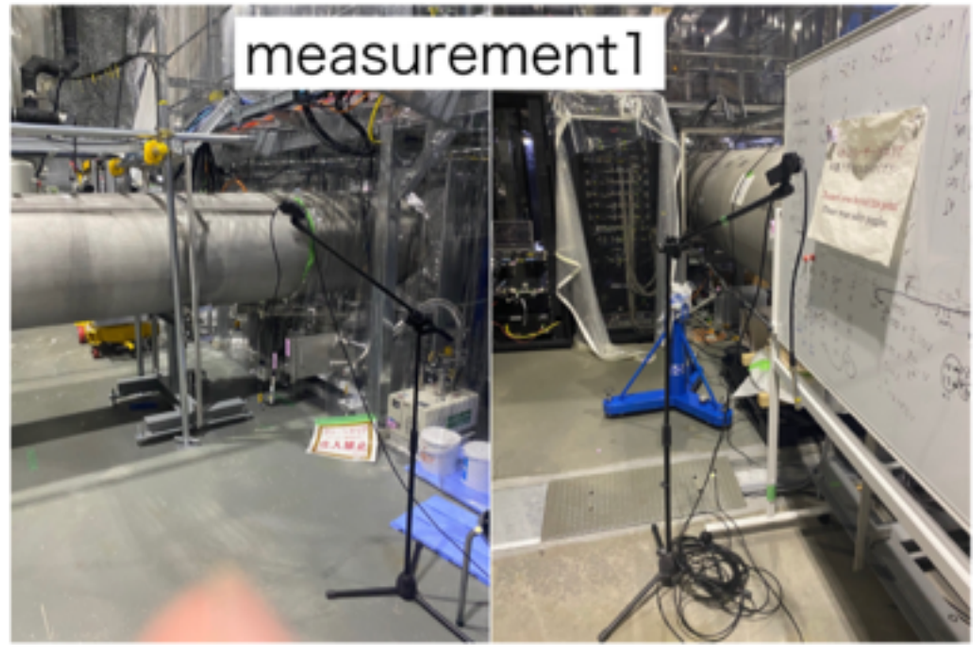

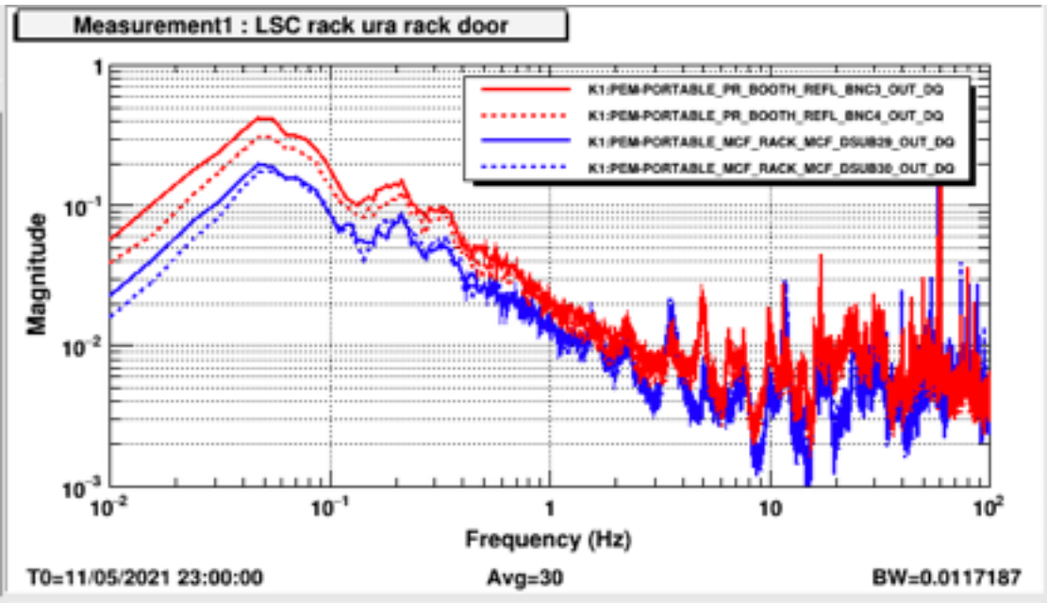

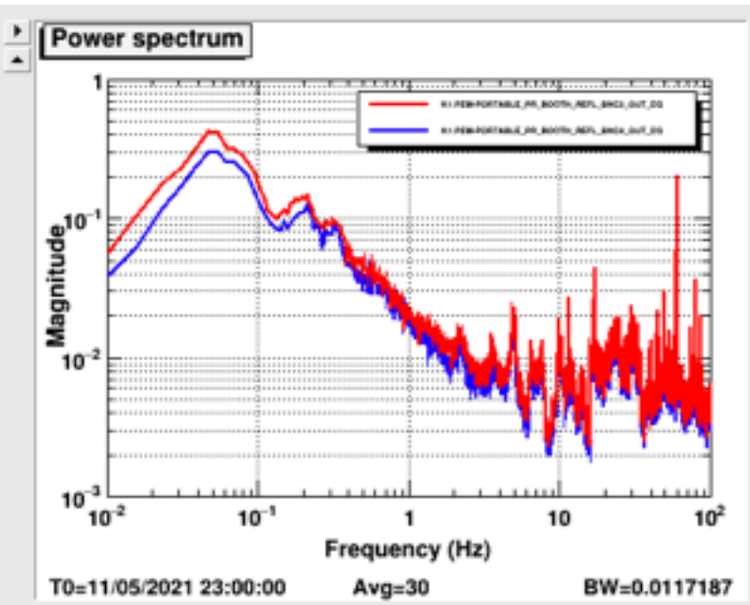

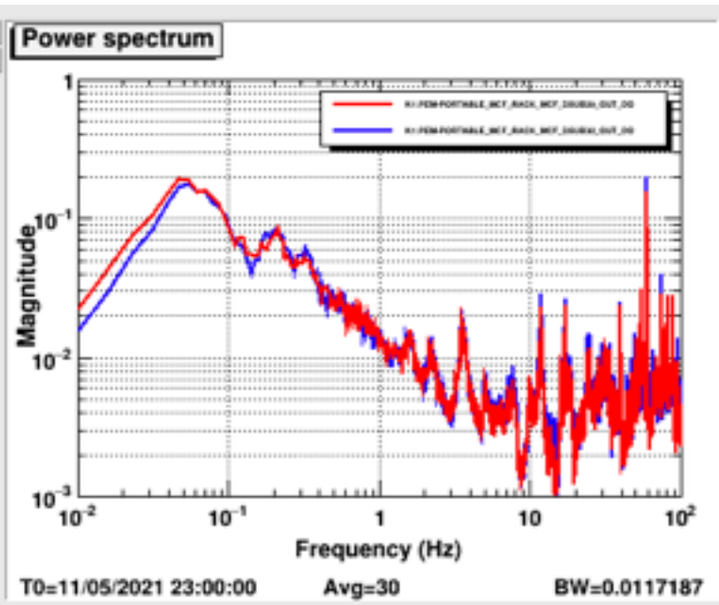

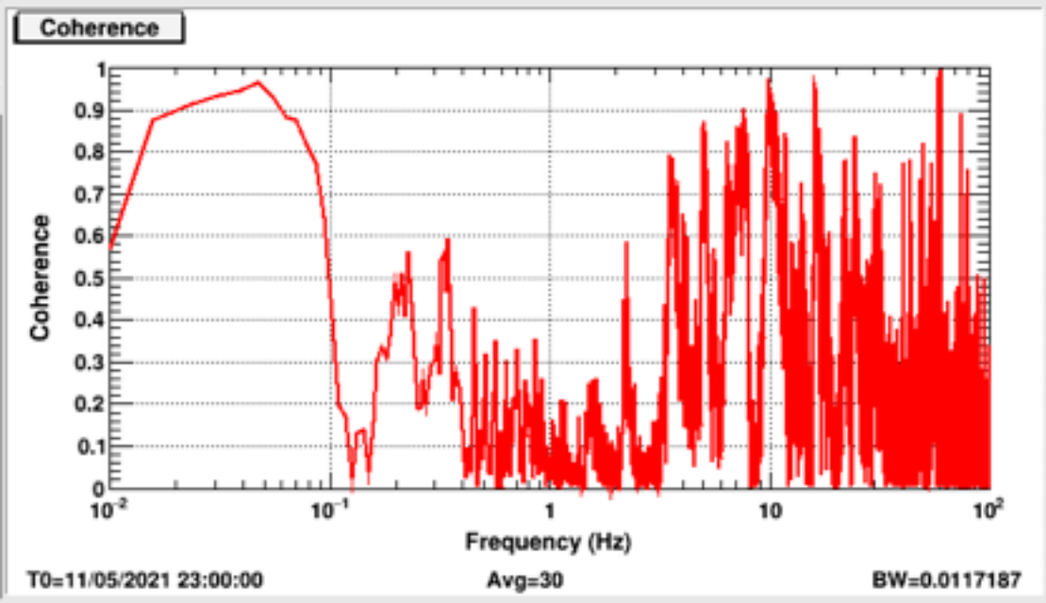

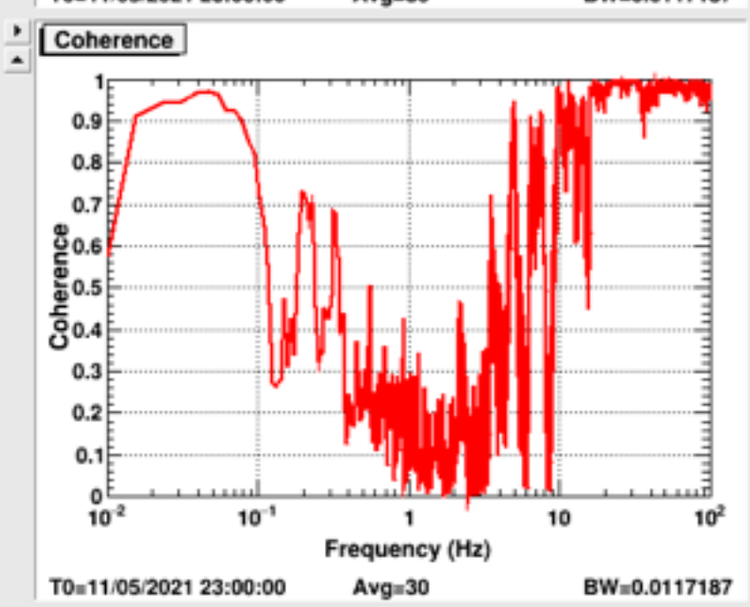

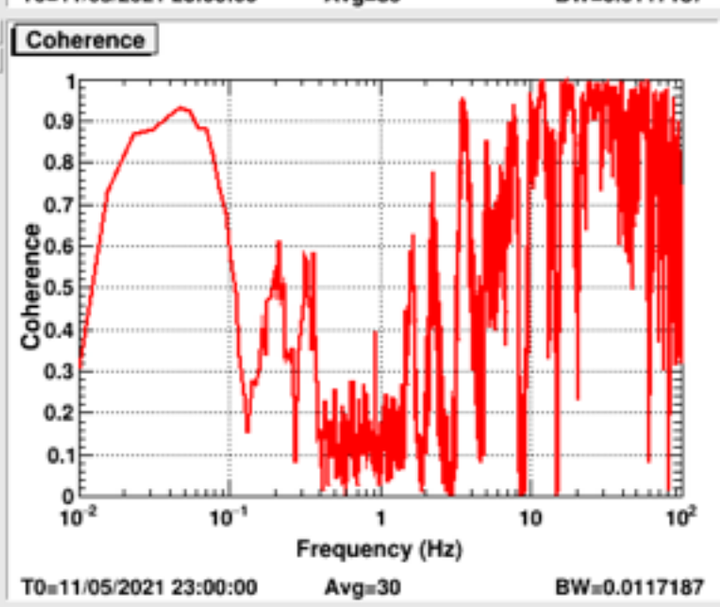

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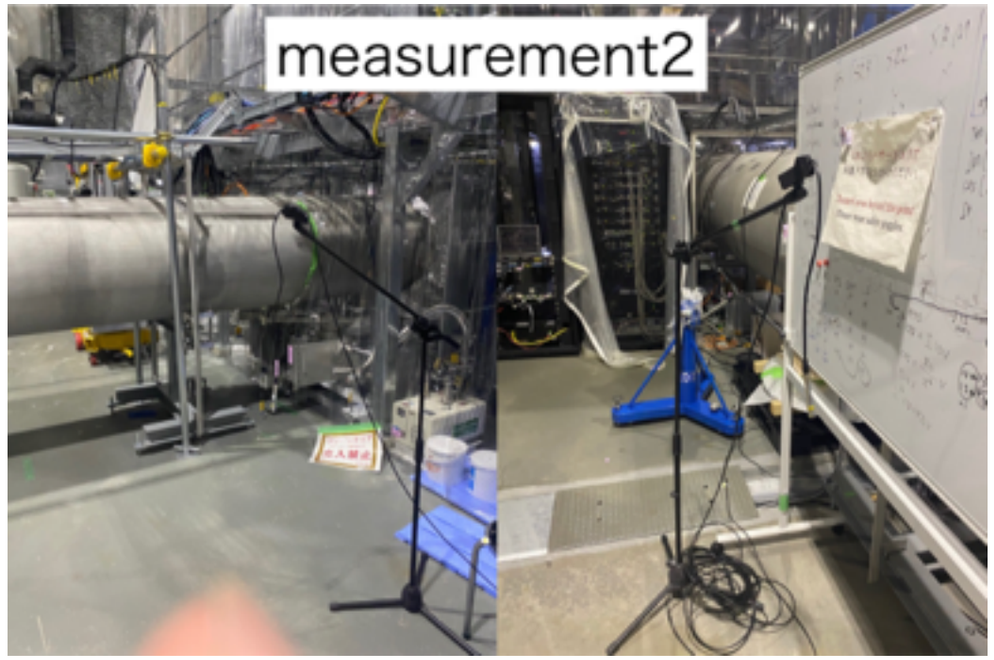

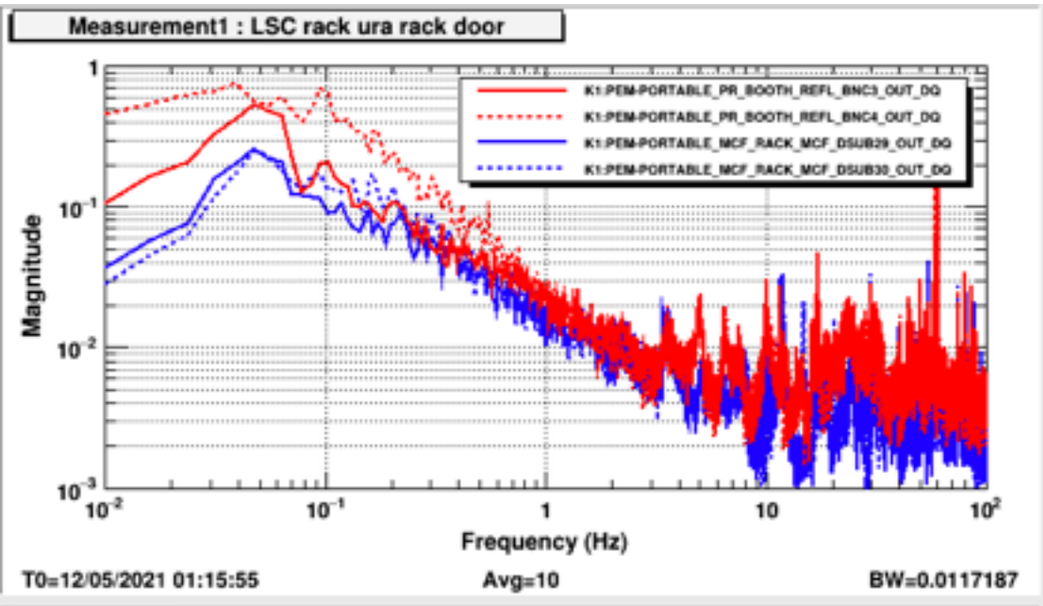

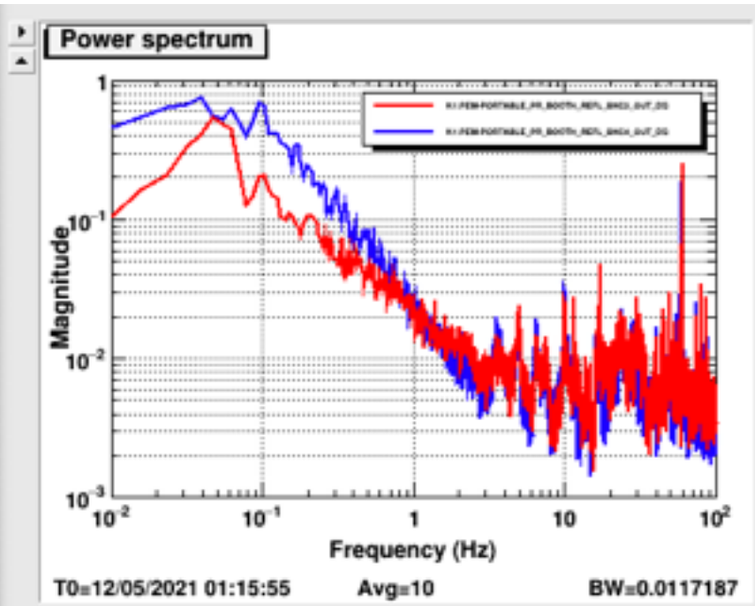

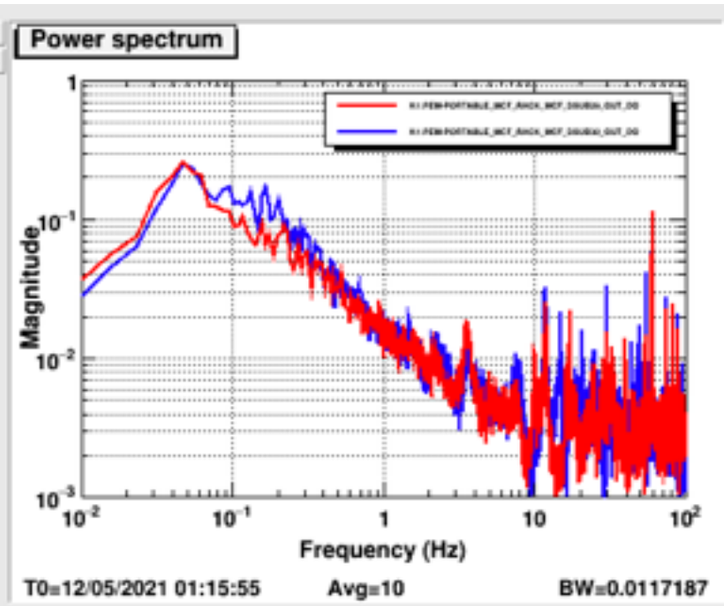

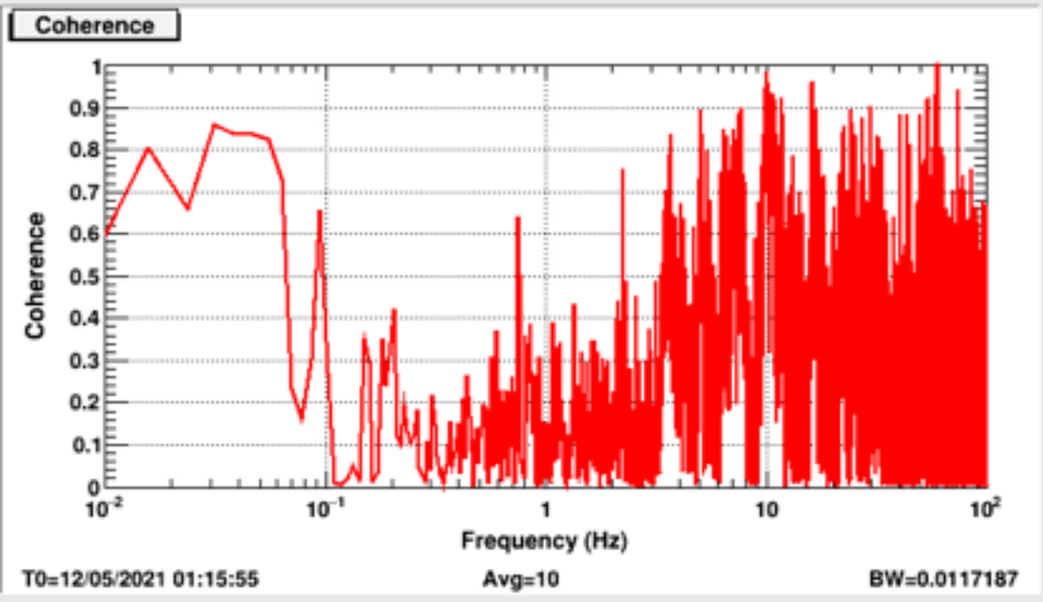

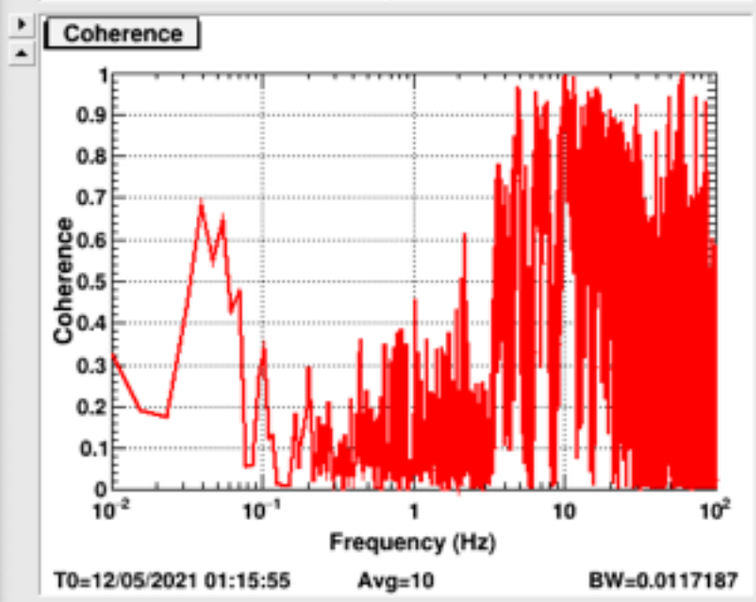

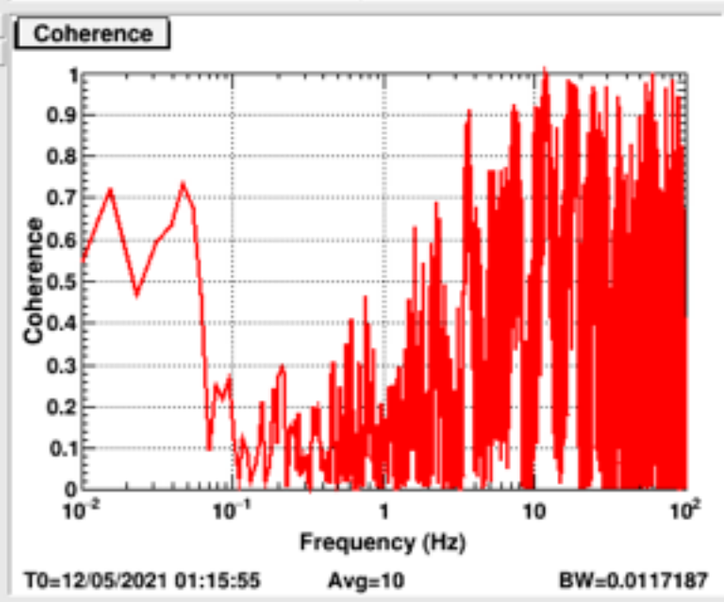

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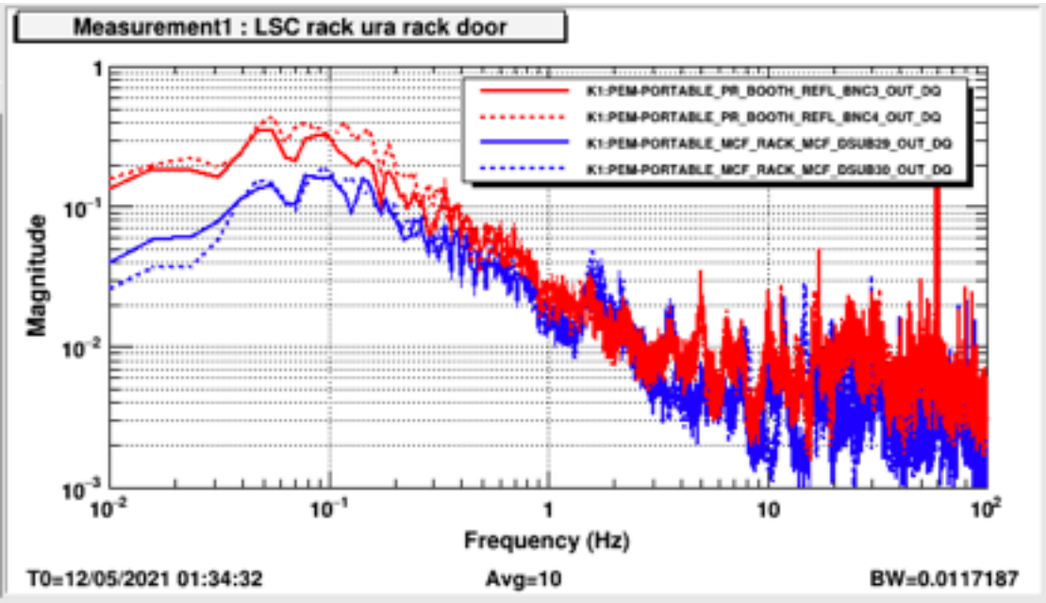

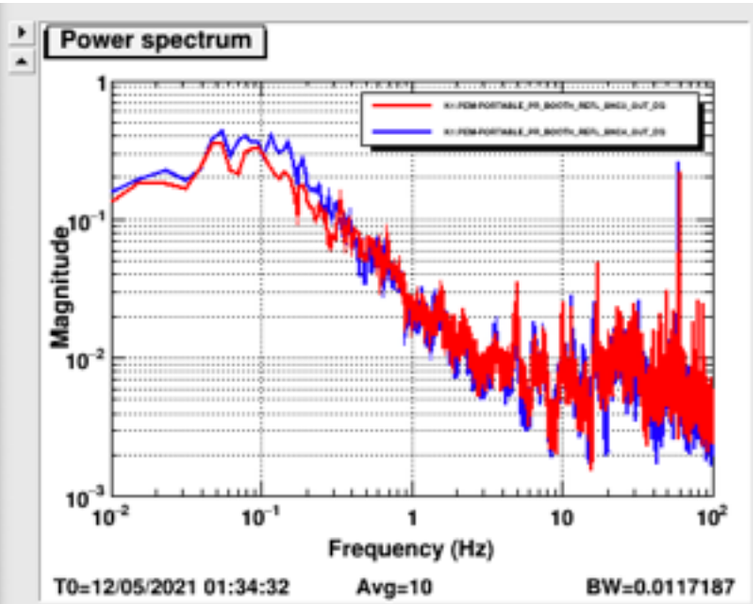

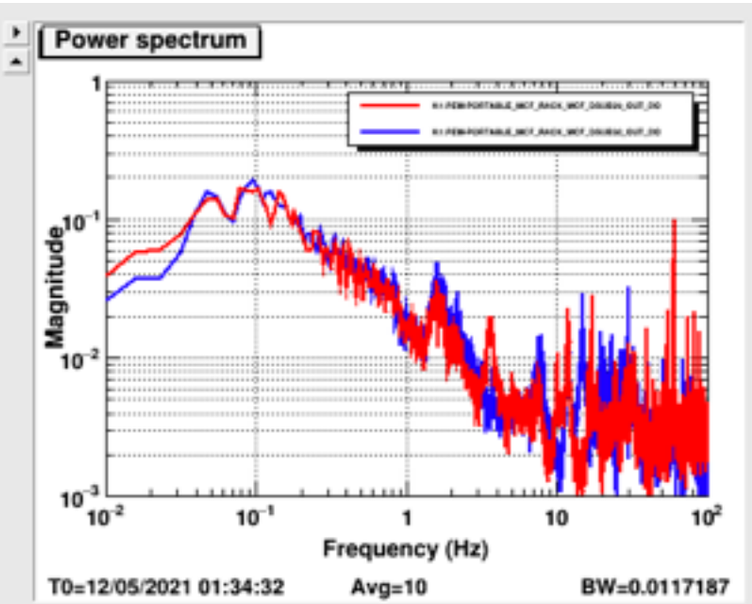

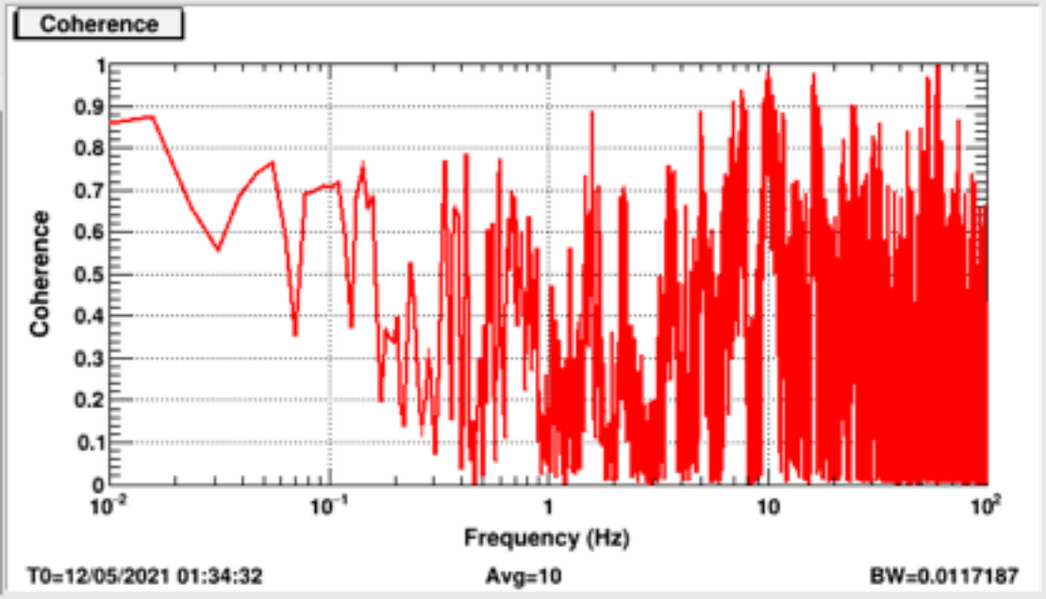

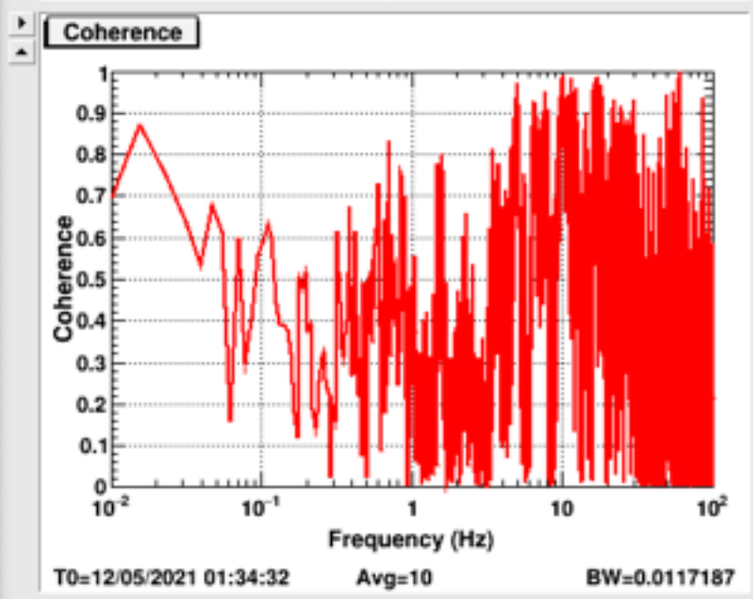

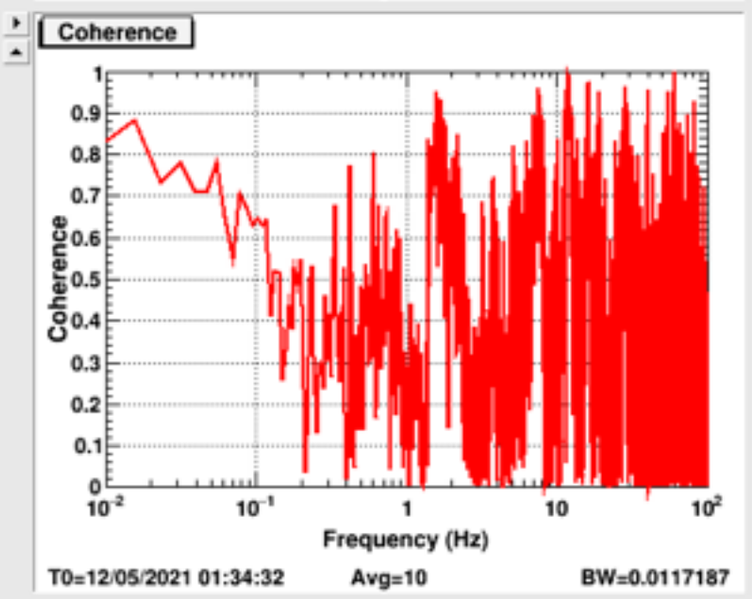

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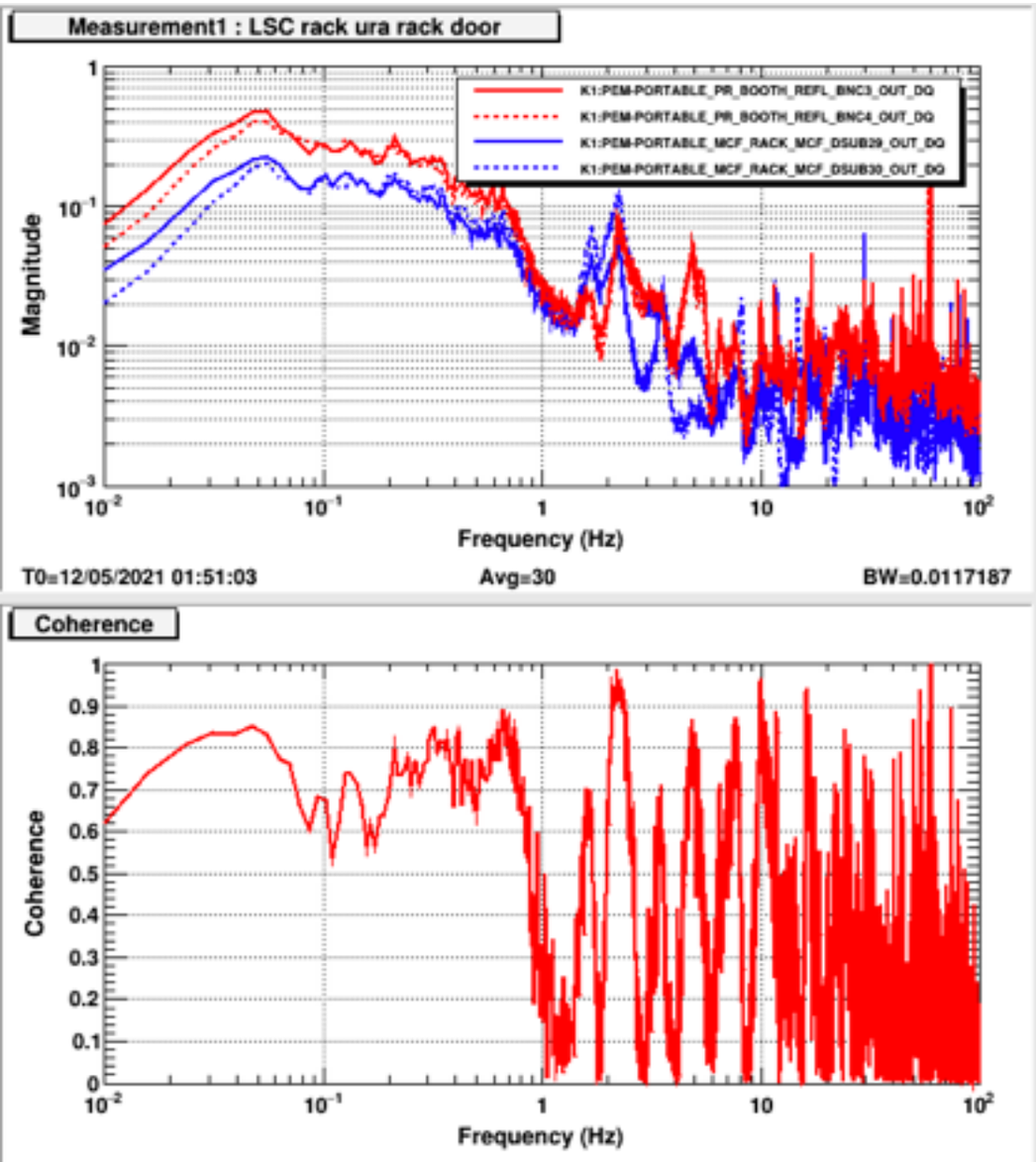

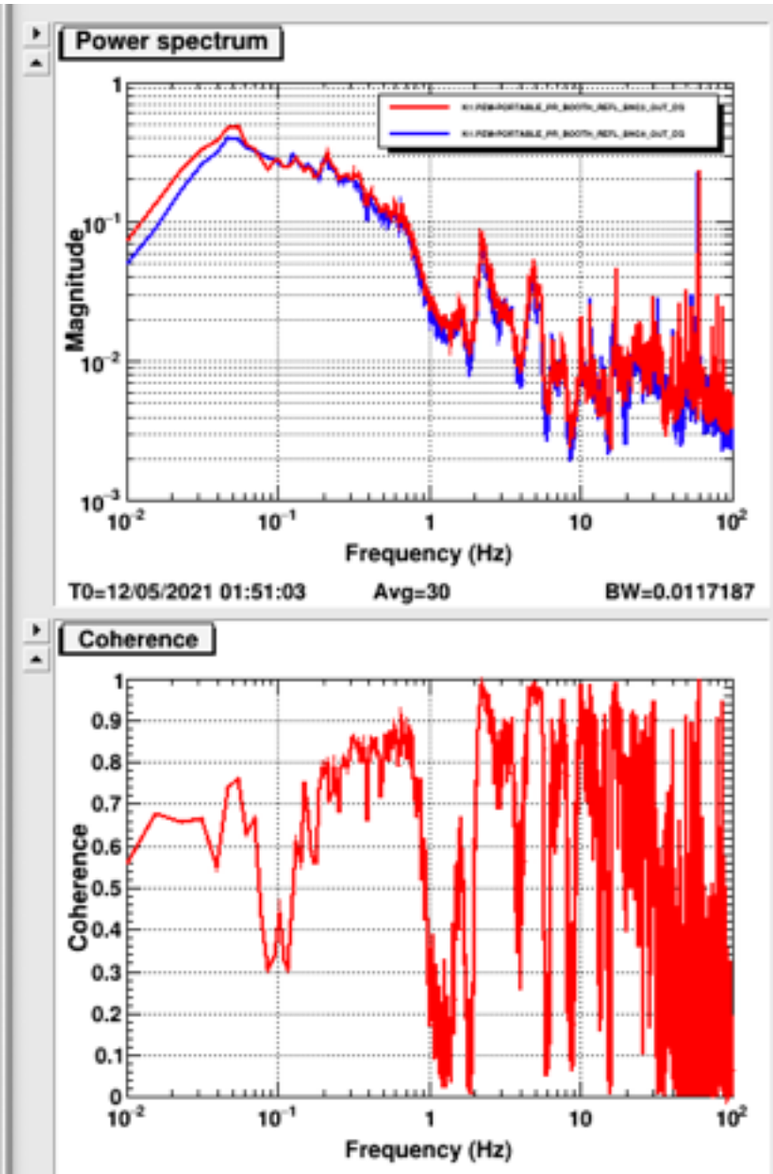

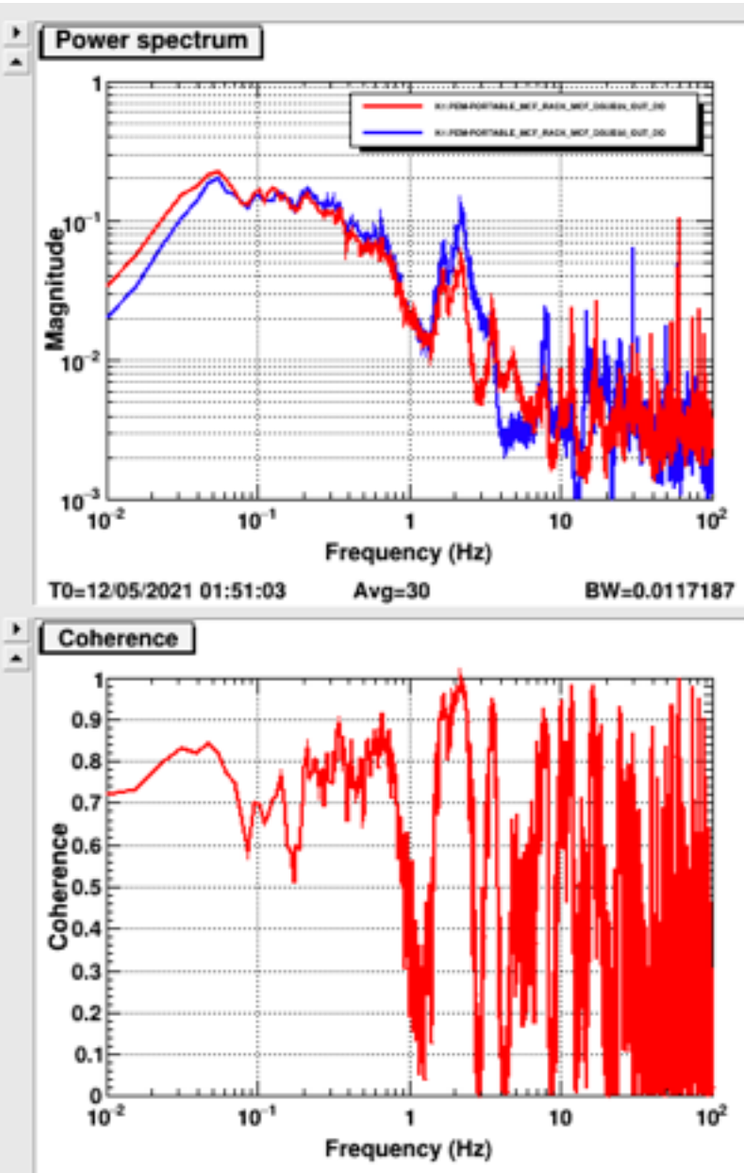

Infrasound + various position

空間の大きさや音源の方向から何かしら違いが怒るかと思ったが、それよりも環境変化が大きすぎて、まずは、同じ場所で長時間置いて時間変化や突発的なものを見るのがいいと思います。地震も影響を与えている？？

Infrasound + seismometer -> Ongoing